

Complementary modelling tools

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WP8: Work Package Overview

- Task 8.1: Coordination (UM, CERN, GSI, ELI)
- Task 8.2: Impact of low energy particles on SEU rate prediction (UM)
- Task 8.3: Circuit level modelling (UM)
 - Task 8.4: Facility modelling (CERN, GSI, ELI)
 - → Task 8.5: Dose Effect with ECORCE (UM)
 - → Task 8.6: Integration of SEE event-by-event scoring in FLUKA (CERN)



Deliverables and milestones

T0+18	dec-22	D8.1	Frederic Wrobel	+ Ygor Aguiar	+ Cleiton Marques				
		M8.1	Roberto Versaci	+ All	+ Postdocs				
		D8.2	Roberto Versaci	+ Jérôme Boch	+ Postdocs				
T0+24	june-23	D8.3	Frederic Wrobel	+ Ygor Aguiar	+ Cleiton Marques				
T0+30	dec-23	D8.4	Frederic Wrobel	+ Ygor Aguiar	+ Cleiton Marques				
		M8.2	Alain Michez	+ Jérôme Boch					
T0+36	june-24	M8.3	David Lucsanyi	+Giuseppe Lerner	+ Gabrielle Hugo				
T0+42	dec-24	D8.5	Alain Michez	+ Jérôme Boch					
D8.1	Simulation results of the importance of 1-10MeV energy range on the SER for neutrons (T0+18months)								
D8.2	Modelling of the X-Ray generator and Co60 source (T0+18months)								
D8.3	Recommendation for simulating low energy protons (T0+24months)								
D8.4	Simulation results and report on circuit modelling (T0+30months)								
D8.5	.5 Determination of the fitting parameters for the target device and comparison with the experimental results (T0+42months								
M8.1	Facility modelling for RADNEXT experimental conditions (modelling released and simulations are running at T0+18months)								
M8.2	ECORCE evaluation (Modelling released and simulations are running at T0+30months)								
M8.3	Validation of Fluka SEE module (Report including benchmark results and instructions for users at T0+36months)								
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D8.4: Simulation results and report on circuit modelling (T0+30months)

- Spice model often not known => use of a basic transistor model (source current and node capacitance)
- Parameters are taken to be representative of the technology
- Monte Carlo tool used: PredicSEE



Fig. 16. Heavy ions SEU cross-section for 90 nm 6T SRAM [Fig. 17. Heavy ion SEU cross-section for 65 nm SRAM [21] Fig. 18. Heavy ion SEU cross-section for 45 nm SRAM [28]. Fig. 19. Heavy ion SEU cross-section for 32 nm 6T SRAM [29].

 Good agreement with experimental data, though some discrepancies at low LET for 32nm node.



D8.4: Simulation results and report on circuit modelling (T0+30months)

Effect of voltage 10-8 SEU Cross Section (cm²/bit) Simplified Literature Model 10-9 1.2 V 10 20 30 40 0 50 LET (MeV.cm²/mg)

Fig. 20. Voltage scaling result for heavy ion SEU cross-section at 65nm [21].

Very good agreement with experimental data





M8.2: ECORCE evaluation (T0+30months)

TCAD modeling: solve differential equations in semiconductors and insulators

- → Poisson
- \rightarrow electron and hole transport equations
- \rightarrow heat equation
- \rightarrow electron and hole trapping equations

First step: create the model based on technology node

- \rightarrow get technological informations
- \rightarrow fit experimental Id=f(Vgs)
- \rightarrow need to adjust the model parameters

Microchip microcontroler using 150nm technology node

This study \rightarrow Microchip 150nm technology node.

TCAD tool: ECORCE (Etude du COmportement sous Radiation des Composants Electroniques)

Question: what parameters should be adjusted ?





Effect of parameter variation on the Id=f(Vgs) characteristic

Threshold

voltage

Leakage current

To answer \rightarrow analyze of parameter variation on Id=f(Vgs)

1E-04

1E-06

1E-08

1E-10

1E-12

l_{drain} (A/μm)

3 values of the Id=f(Vgs) characteristic selected

Effect of 6 parameters analyzed

RAC





Structure of a 1.8V NMOS transistor of the 180nm Microchip technology, approximate values for privacy concern

Id=f(Vgs) fitting with these information

First result: high interface trap density for pristine devices (3 10¹¹ cm⁻²)

Saturation

current

Total Ionizing Dose (TID) modeling

Effect of TID \rightarrow positive electric charge in insulators Most often used model: apply fixed charge in the oxide. Weak model since it does not take into account:

- \rightarrow thermal reemission
- \rightarrow trapped carriers recombination by opposite free carriers
- \rightarrow charge displacement induced by the electric field
- \rightarrow change of the electric field induced by trapped charges

ECORCE uses the Curtis model that takes all these phenomena into account.

1E-05 - 1E-07 - Prerad 1E-09 - 100 krad 1E-11 - 300 krad 1E-18 - 1E-17 - 1E-17

Change of the Id=f(Vgs) characteristic of a 5V NMOS of the 150nm Microchip technology induced by 100 krad and 300 krad dose.

O. L. Curtis Jr and J. R. Srour, "The multiple-trapping model and hole transport in SiO2," *J. Appl. Phys.*, vol. 48, no. 9, pp. 3819–3828, 1977.

Next steps: To get TID experimental results from Microchip Compare to TID simulation for 2 transistors



M8.3: Validation of Fluka SEE module (T0+36months)

- SEE simulation features have been implemented for FLUKA.CERN v5 package (under development, not publicly released yet)
- These SEE simulation features have been released to the public as a standalone toolkit called G4SEE
- Experimental validation was successful for neutrons and protons with various SRAMs and silicon diode detector
- Tutorials and user guides are provided for users
- More details in David's presentation (<u>link</u>)



Figure 8: Visualization of particle tracks in micro-metric target geometry during a G4SEE simulation run with 10 MeV protons



Scientific publication and communications

 Frédéric Wrobel, Ygor Aguiar, Cleiton Marques, Giuseppe Lerner, Rubén García Alía, Frédéric Saigné, and Jérôme Boch.

"An Analytical Approach to Calculate Soft Error Rate Induced by Atmospheric Neutrons". MDPI Electronics 2023, 12, 104. https://doi.org/10.3390/electronics12010104.

 Cleiton M. Marques, Leonardo H. Brendler, Frédéric Wrobel, Alexandra L. Zimpeck, Walter E. C. Bartra, Paulo F. Butzen, Cristina Meinhardt.

"A Detailed Electrical Analysis of SEE on 28 nm FDSOI SRAM Architectures". 2023 36th SBC/SBMicro/IEEE/ACM Symposium on Integrated Circuits and Systems Design (SBCCI), Rio de Janeiro, Brazil, 2023, pp. 1-6, doi: 10.1109/SBCCI60457.2023.10261665.

Cleiton M. Marques, Frédéric Wrobel, Ygor Q. Aguiar, Alain Michez, Frédéric Saigné, Jérôme Boch, Luigi Dilillo, and Rubén García Alía.

"Evaluation of a Simplified Modeling Approach for SEE Cross-Section Prediction: A Case Study of SEU on 6T SRAM Cells". MDPI Electronics 2024, 13, 1954.

https://doi.org/10.3390/electronics13101954.



Last deliverable of WP8

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